

1 2 3 4 5 6 7 8 9

A

A

B

B

C

C

D

D

E

E

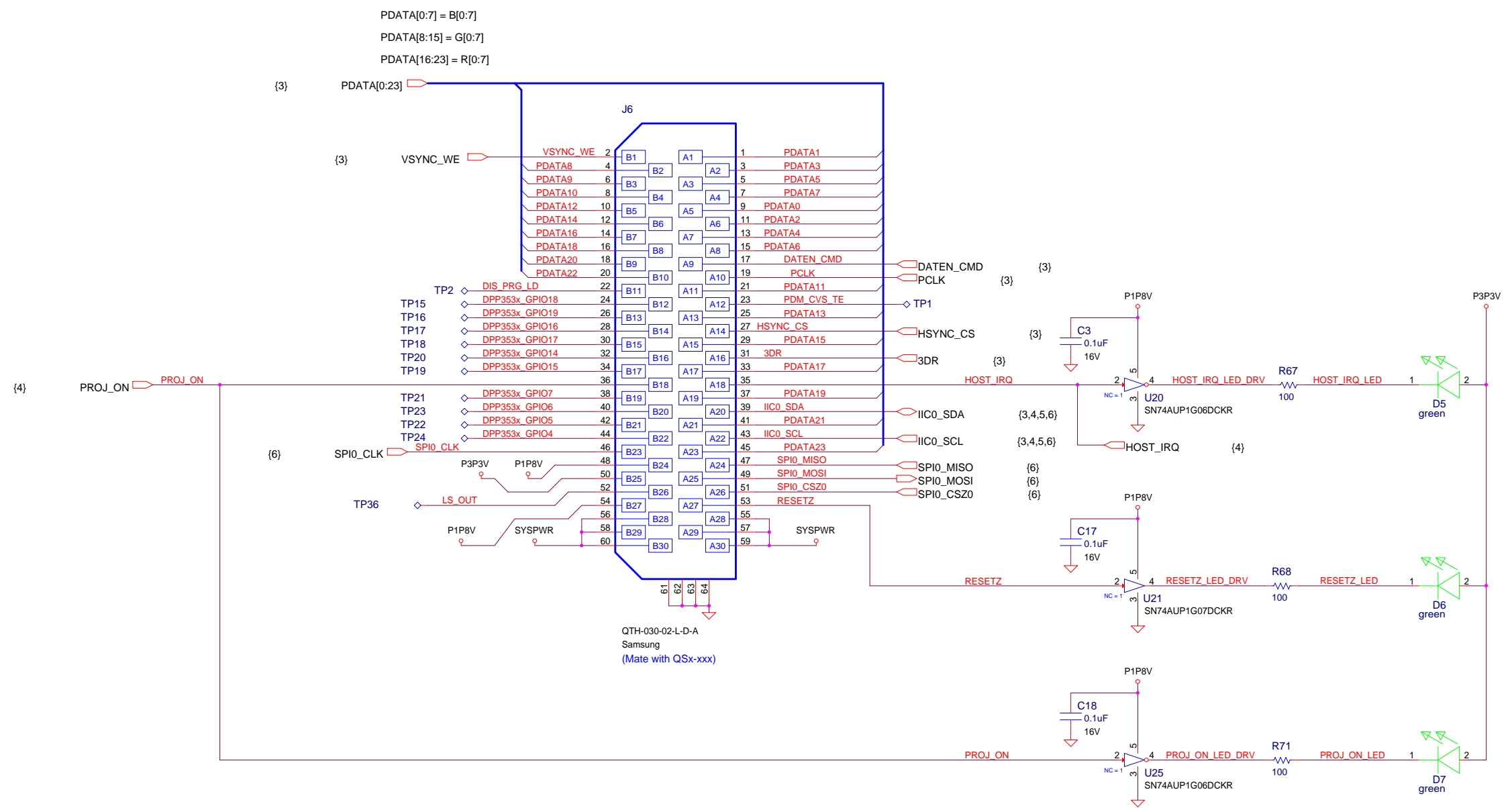
F

F

ESD 2513854
PCB 2513855
CCA 2513856

DWN	Kevin Lowderman	DATE	Jun-05-2014	TEXAS INSTRUMENTS - DLP Products		
ENGR	Kevin Lowderman	DATE	Jun-05-2014	(C) COPYRIGHT 2009 Texas Instruments Inc. All Rights Reserved		
SYS	Dan Morgan	---	---	TITLE	TIDA-00325 DLP LightCrafter Display 2010 Main Board	
APVD	Jeff Dennis	---	---	DRAWING NO	2513854	REV B.1
QA	---	---	---	11 x 17	Orcad Capture 16.2	SHEET 1 of 9

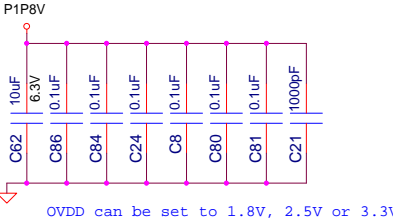
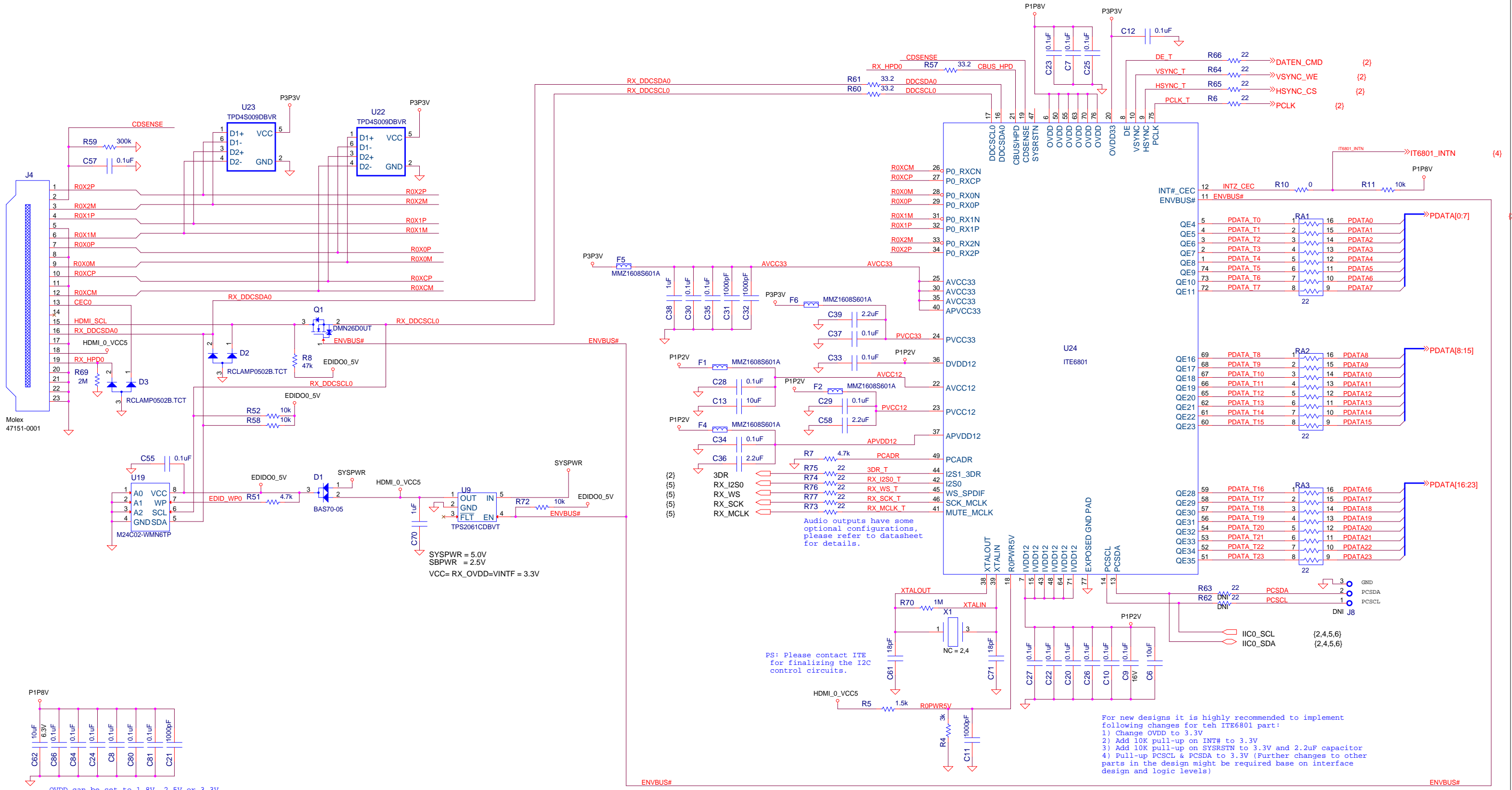
1 2 3 4 5 6 7 8 9



QTH-030-02-L-D-A
Samsung
(Mate with QSx-xxx)

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SYS	Dan Morgan	---	---	TITLE DLP CONNECTION	
APVD	Jeff Dennis	---	---	DRAWING NO	2513854
QA	---	---	---	REV	B.1
			11 x 17	Orcad Capture 16.2	SHEET 2 of 9

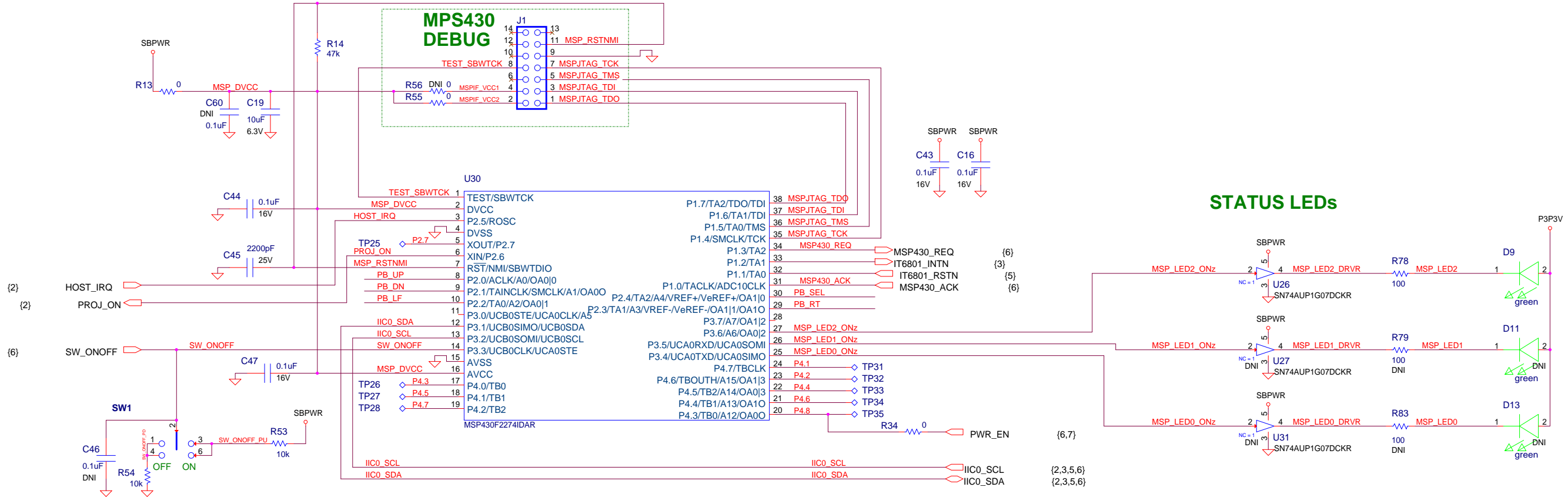


PS: Please contact ITE for finalizing the I2C control circuits.

For new designs it is highly recommended to implement following changes for teh ITE6801 part:
 1) Change OVDD to 3.3V
 2) Add 10K pull-up on INT# to 3.3V
 3) Add 10K pull-up on SYSRSTN to 3.3V and 2.2uF capacitor
 4) Pull-up PCSCl & PCSDA to 3.3V (Further changes to other parts in the design might be required base on interface design and logic levels)

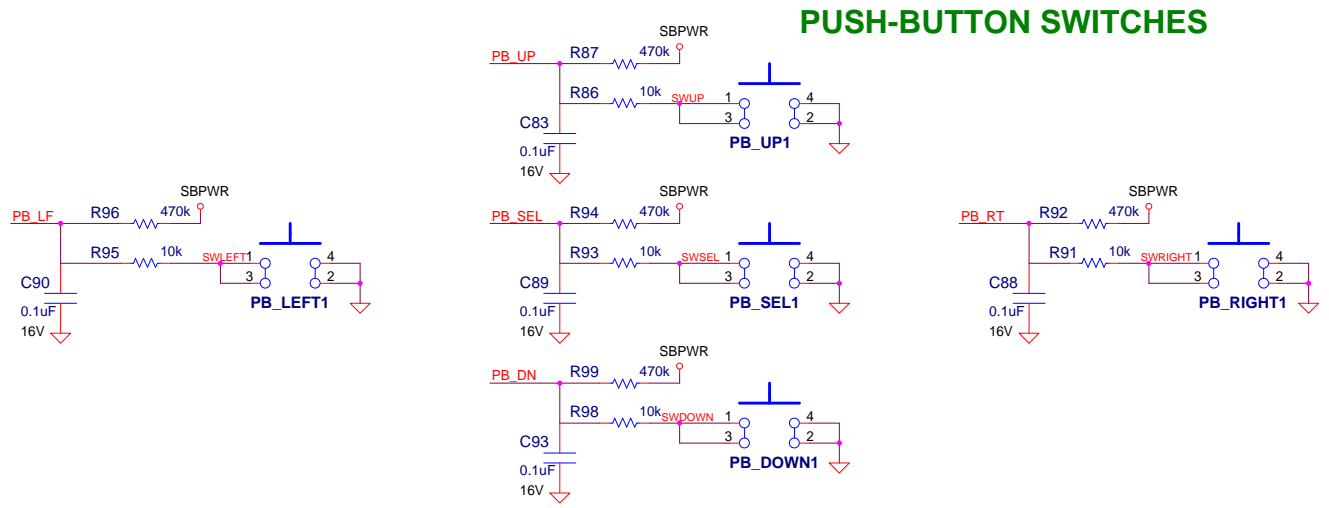
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ENGR	Kevin Lowderman	DATE	Jun-05-2014	(C) COPYRIGHT 2009 Texas Instruments Inc. All Rights Reserved	
SYS	Dan Morgan			TITLE	ITE6801
APVD	Jeff Dennis			DRAWING NO	2513854
QA				REV	B.1
				11 x 17	Orcad Capture 16.2 SHEET 3 of 9



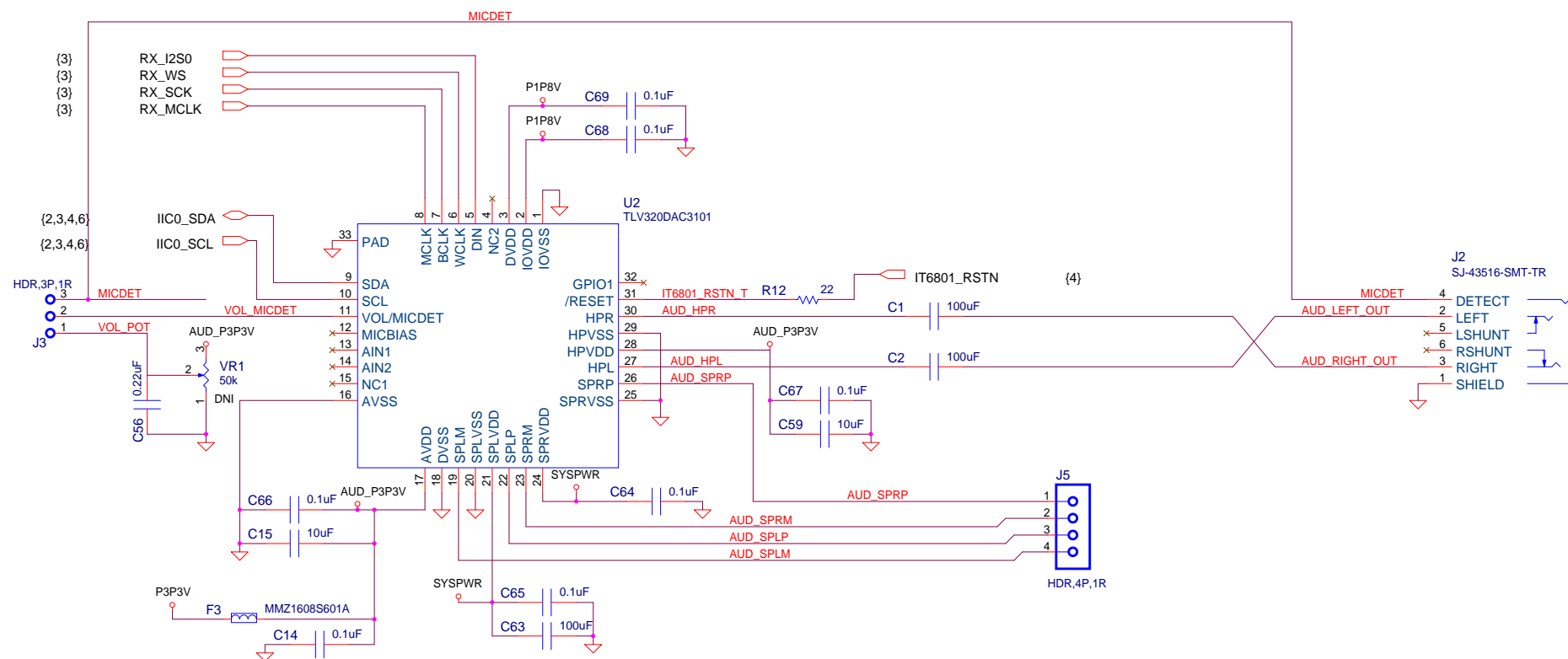
STATUS LEDs

PUSH-BUTTON SWITCHES



PRELIMINARY

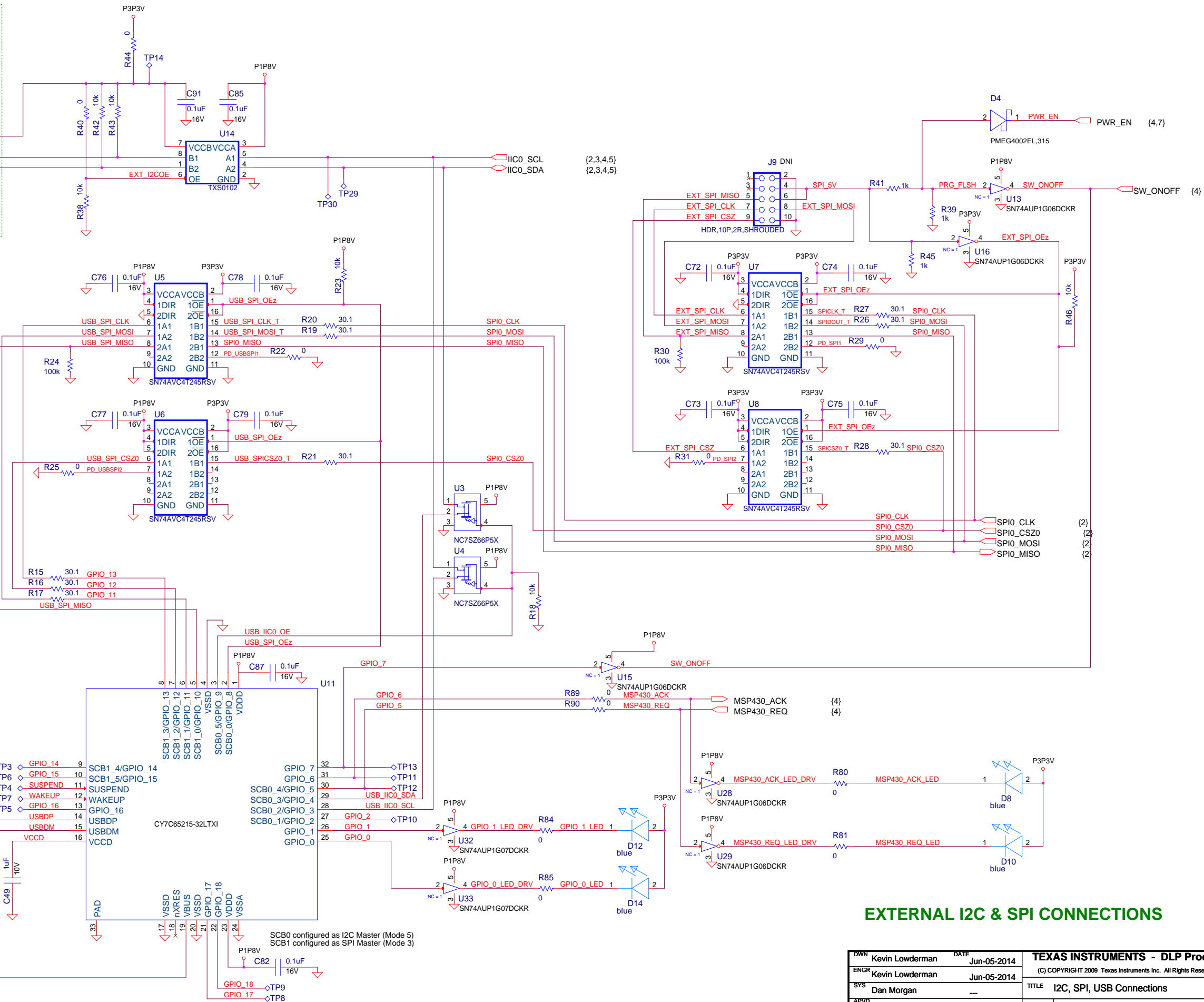
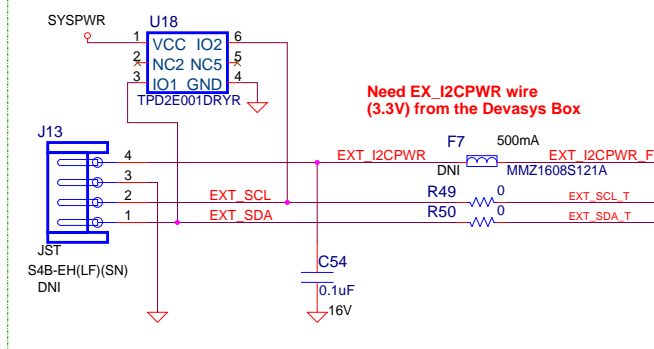
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ENGR	Kevin Lowderman		Jun-05-2014	(C) COPYRIGHT 2009 Texas Instruments Inc. All Rights Reserved	
SYS	Dan Morgan		---	TITLE SYSTEM CONTROLLER	
APVD	Jeff Dennis		---	DRAWING NO	2513854
QA	---		---	REV	B.1
			11 x 17	Orcad Capture 16.2	SHEET 4 of 9



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SYS	Dan Morgan	---	---	TITLE AUDIO OUT	
APVD	Jeff Dennis	---	---	DRAWING NO	2513854
QA	---	---	---	REV	B.1
11 x 17		Orcad Capture 16.2	SHEET 5 of 9		

DEVASYS CONNECTOR

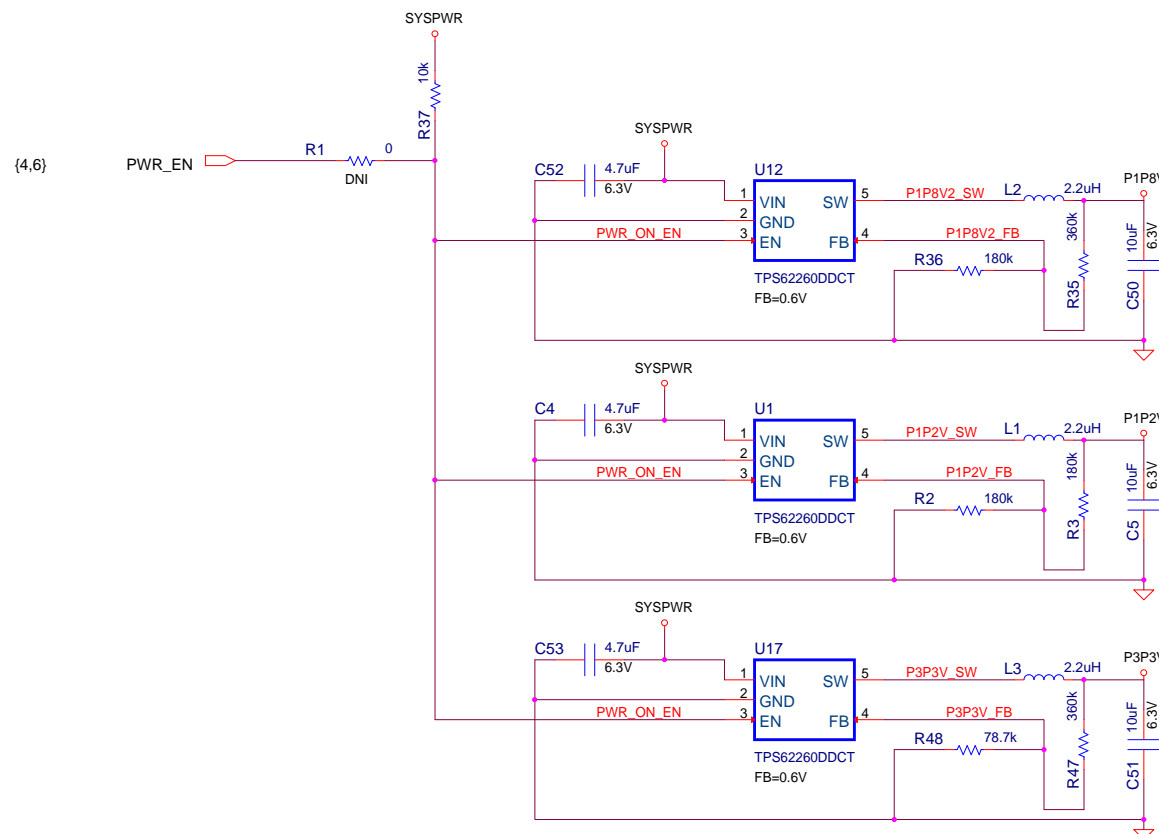
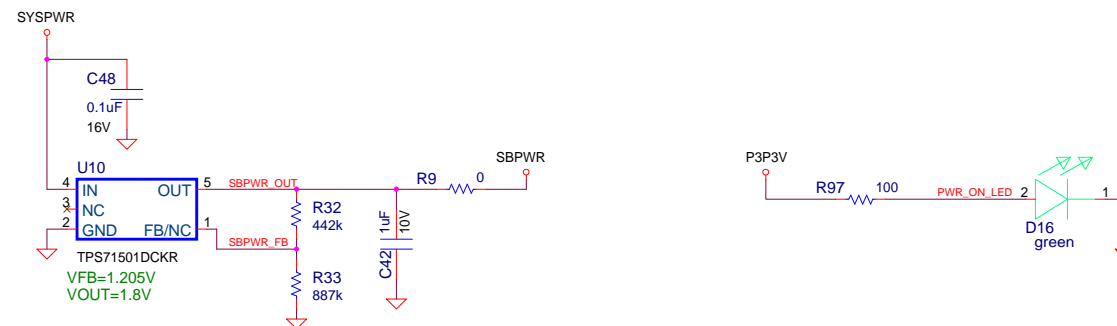
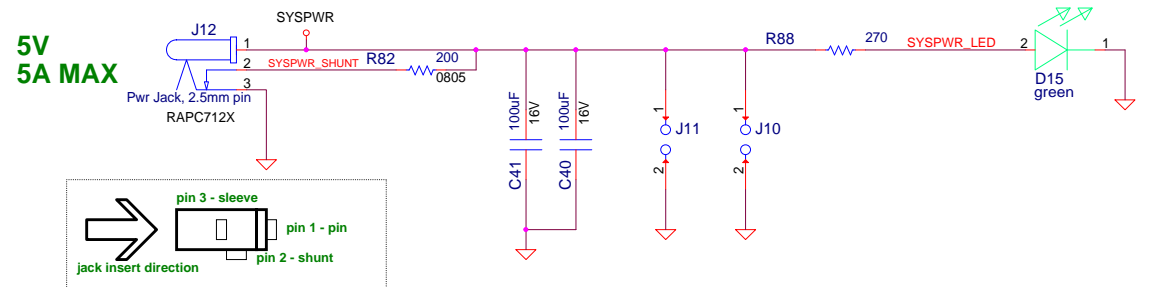


EXTERNAL I2C & SPI CONNECTIONS

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ENGR	Kevin Lowderman	DATE	Jun-05-2014		
SYS	Dan Morgan	---	---	TITLE	I2C, SPI, USB Connections
APVD	Jeff Dennis	---	---	DRAWING NO	2513854
QA	---	---	---	REV	B.1

PRELIMINARY

EXTERNAL POWER INPUT



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SYS	Dan Morgan		---	TITLE Power Supplies	
APVD	Jeff Dennis		---	DRAWING NO	2513854
QA	---		---	REV	B.1
			11 x 17	Orcad Capture 16.2	SHEET 7 of 9

Revisions

Rev. 0.0 : Development version

Rev. A.0 : Initial Release

- R14 changed to 47k, C45 changed to 2200pf
- U2 pin 2 disconnected from 3.3V and connected to 1.8V
- Add net SCL_IFP to IIC0_SCL
- Add net SDA_IFP to IIC0_SDA

Rev. B.0 : Do not install unused connectors, etc.

- VR1, J9, J13,

Rev. B.1: Added note for future designs to ITE6801 page

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SYS	Dan Morgan	---	---	TITLE Revision Notes	
APVD	Jeff Dennis	---	---	DRAWING NO	2513854
QA	---	---	---	REV	B.1
		11 x 17	Orcad Capture 16.2	SHEET	8 of 9

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